

A1 37. A chip scale packaged crystalline substrate based device comprising:
a crystalline substrate having formed thereon a microstructure; and
at least one chip scale package comprising at least one transparent packaging layer
which is sealed over said microstructure by means of an adhesive and defines therewith at least
one gap between said crystalline substrate and said at least one packaging layer,
wherein said microstructure receives light via said at least one transparent packaging
layer.

Amend claims 1, 6, 10, 16, 20, 26 and 32 as follows.

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A2 1. (Amended) A crystalline substrate based device comprising:
a crystalline substrate having formed thereon a microstructure; and
at least one transparent packaging layer which is sealed over said microstructure by
means of an adhesive and defines therewith at least one gap between said crystalline
substrate and said at least one packaging layer,
wherein said microstructure receives light via said at least one transparent packaging
layer.

A3 6. (Amended) A crystalline substrate based device according to claim 1 and
wherein said at least one gap comprises a plurality of gaps.

A4 10. (Amended) A chip scale packaged crystalline substrate comprising:
a substrate having formed thereon a microstructure;

at least one chip scale package which is sealed over said microstructure and defines therewith at least one gap, and

wherein said at least one package is at least partially transparent.

16. (Amended) A chip scale packaged crystalline substrate according to claim 10 and wherein said at least one gap comprises a plurality of gaps.

20. (Amended) A method of producing a crystalline substrate based device comprising:
providing a microstructure on a substrate; and
adhesively sealing at least one packaging layer over said microstructure and at least partially spaced therefrom, thereby to define a gap between said microstructure and said at least one packaging layer,
wherein said at least one packaging layer is transparent.

26. (Amended) A method of producing a crystalline substrate based device according to claim 20 and wherein said at least one gap comprises a plurality of gaps.

32. (Amended) A device according to claim 1 and wherein said microstructure comprises a surface acoustic wave device.